

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claims 1, 4, 21 and 41.

Listing of Claims:

1. (Currently Amended) A leadframe adapted to prevent mold compound flash debris, comprising:

a pair of leadframe rails extending longitudinally along opposite sides of the leadframe and adapted to engage surfaces on upper and lower mold sections to form a gasket; and

a respective mold compound adherence area formed on each of the leadframe rails, the mold compound adherence area occupying a major portion of a longitudinal dimension of each of the pair of leadframe rails and adapted to abut a surface of the upper or lower mold section, the mold compound adherence area having reduced surface roughness that causes a mold compound to adhere to the mold compound adherence area less securely than portions of the leadframe outside the mold compound adherence area.

2-3. (Canceled)

4. (Currently Amended) The leadframe of claim 1 wherein the mold compound adherence areas are formed on opposite surfaces of the respective leadframe rails and each are positioned to abut one of the upper and lower mold sections.

5-7. (Canceled)

8. (Previously Presented) The leadframe of claim 1 wherein each of the mold compound adherence areas comprises an polished area of a respective one of the leadframe rails.

9. (Canceled)

10. (Previously Presented) The leadframe of claim 8 wherein each of the polished areas comprises a mechanically polished area of a respective one of the leadframe rails.

11. (Previously Presented) The leadframe of claim 8 wherein each of the polished areas of surface roughness comprise a chemically polished area of a respective one of the leadframe rails.

12. (Previously Presented) The leadframe of claim 8 wherein the polished areas comprise an area of a material on each of the leadframe rails that is the same as a material used to form another portion of the leadframe.

13-19. (Canceled)

20. (Original) The leadframe of claim 1, further comprising:
a plurality of integrated circuit attachment panels; and
a plurality of leads extending from each of the integrated circuit attachment panels.

21. (Currently Amended) An injection mold for molding a package for an integrated circuit, the injection mold comprising:

a first mold section including a plurality of mold cavities;
a second mold section including a plurality of mold cavities corresponding in number to the number of cavities included in the first mold section and having a size and a shape corresponding to the size and shape of the mold cavities in the first mold section, at least one of the first and second mold section including a plurality of inlet channels each providing a fluid path into one of the plurality of mold cavities and at least one of the first and second mold sections includes a plurality of vent channels each providing a fluid path away from one of the plurality of mold cavities; and

a leadframe positioned between the first and second mold sections, the leadframe having a pair of leadframe rails extending along opposite sides of the leadframe across the inlet and vent channels, the leadframe further including a respective mold compound adherence area formed on each of the leadframe rails and extending adjacent the inlet and vent channels, the

mold compound adherence area having reduced surface roughness that causes a mold compound to adhere to the mold compound adherence area less securely than portions of the leadframe outside the mold compound adherence area.

22. (Original) The injection mold of claim 21 wherein a respective injection inlet adjacent is formed adjacent each of the mold cavities in the second mold section, and a respective mold vent is formed adjacent each of the mold cavities in the second mold section on adjacent an edge of the mold cavity opposite the injection inlet for the mold cavity in the second mold section.

23-24. (Canceled)

25. (Original) The injection mold of claim 21 wherein the mold compound adherence areas are formed on opposite surfaces of the respective leadframe rails.

26-28. (Canceled)

29. (Previously Presented) The injection mold of claim 21 wherein each of the mold compound adherence areas comprises an polished area formed on a respective one of the leadframe rails.

30. (Canceled)

31. (Previously Presented) The injection mold of claim 21 wherein each of the polished areas comprises a mechanically polished area of a respective one of the leadframe rails.

32. (Previously Presented) The injection mold of claim 21 wherein each of the polished areas comprises a chemically polished area of a respective one of the leadframe rails.

33. (Previously Presented) The injection mold of claim 29 wherein the polished areas comprise an area of material on each of the leadframe rails that is the same as a material used to form another portion of the leadframe.

34-39. (Canceled)

40. (Original) The injection mold of claim 21, further comprising:
a plurality of integrated circuit attachment panels; and
a plurality of leads extending from each of the integrated circuit attachment panels.

41. (Currently Amended) An injection molding machine for molding integrated circuit packages, comprising:

a first mold section including a plurality of mold cavities;
a second mold section including a plurality of mold cavities corresponding in number to the number of cavities included in the first mold section and having a size and a shape corresponding to the size and shape of the mold cavities in the first mold section, at least one of the first and second mold section including a plurality of inlet channels each providing a fluid path into one of the plurality of mold cavities and at least one of the first and second mold sections includes a plurality of vent channels each providing a fluid path away from one of the plurality of mold cavities;

a material reservoir containing a supply of a mold compound that is to be injected into the mold cavities;

an injection mechanism in fluid communication with the material reservoir and the injection vents, the injection mechanism forcibly injecting the mold compound from the material reservoir into the mold cavities;

a heating mechanism for heating the mold sections; and

a leadframe positioned between the first and second mold sections, the leadframe having a pair of leadframe rails extending along opposite sides of the leadframe across the inlet and vent channels, the leadframe further including a respective mold compound adherence area formed on each of the leadframe rails and extending adjacent the inlet and vent channels, the mold compound adherence area having reduced surface roughness that causes a mold compound

to adhere to the mold compound adherence area less securely than portions of the leadframe outside the mold compound adherence area.

42. (Original) The injection molding machine of claim 41 wherein a respective injection inlet adjacent is formed adjacent each of the mold cavities in the second mold section, and a respective mold vent is formed adjacent each of the mold cavities in the second mold section on adjacent an edge of the mold cavity opposite the injection inlet for the mold cavity in the second mold section.

43-44. (Canceled)

45. (Original) The injection molding machine of claim 41 wherein the mold compound adherence areas are formed on opposite surfaces of the respective leadframe rails.

46-48. (Canceled)

49. (Previously Presented) The injection molding machine of claim 41 wherein each of the mold compound adherence areas comprises an polished area formed on a respective one of the leadframe rails.

50. (Canceled)

51. (Previously Presented) The injection molding machine of claim 49 wherein each of the polished areas comprises a mechanically polished area of a respective one of the leadframe rails.

52. (Previously Presented) The injection molding machine of claim 49 wherein each of the polished areas comprises a chemically polished area of a respective one of the leadframe rails.

53. (Previously Presented) The injection molding machine of claim 49 wherein the polished area comprises an area of a material on each of the leadframe rails that is the same as a material used to form another portion of the leadframe.

54-59. (Canceled)

60. (Original) The injection molding machine of claim 41, further comprising:
a plurality of integrated circuit attachment panels; and
a plurality of leads extending from each of the integrated circuit attachment panels.

61-100 (Canceled)